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HERMETICALLY PACKAGING A MICROELECTROMECHANICAL
SWITCH AND A FILM BULK ACOUSTIC RESONATOR

Abstract of the Disclosure

A film bulk acoustic resonator wafer and microelectro-
mechanical switch wafer may be combined together in face-
to-face abutment with sealing material between the wafers
5 to define individual modules. Electrical interconnects can
be made between the switch and the film bulk acoustic
resonator within a hermetically sealed chamber defined
between the switch and the film bulk acoustic resonator.